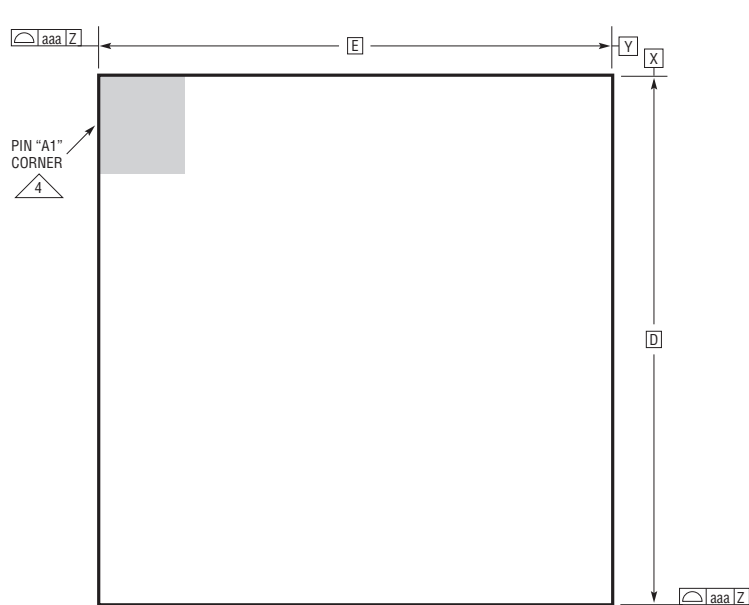
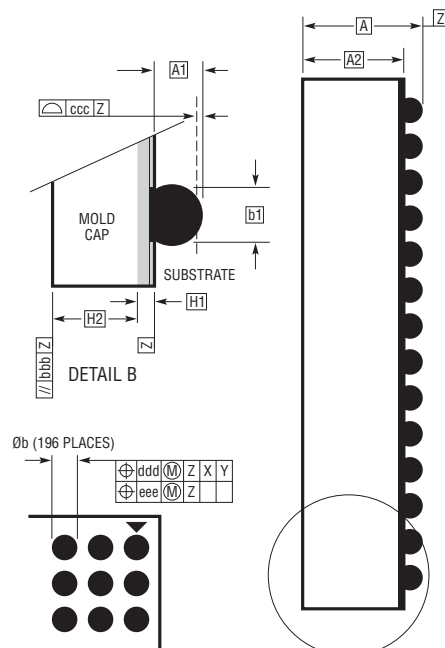


BGA Package
196-Lead (15mm × 15mm × 3.32mm)
 (Reference LTC DWG# 05-08-1970 Rev 0)

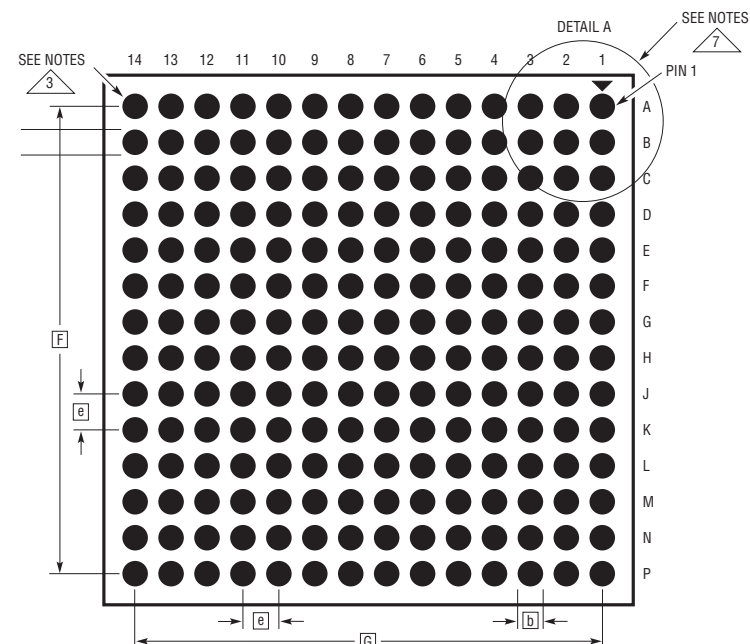


PACKAGE TOP VIEW

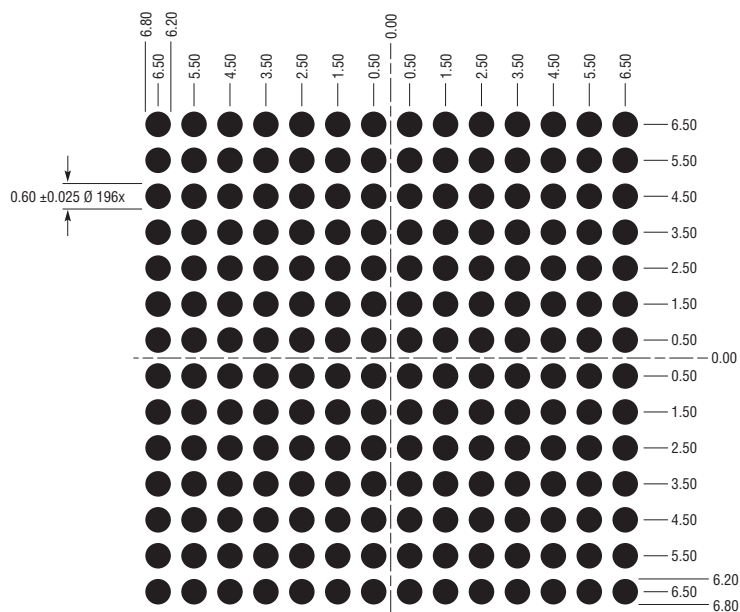


DETAIL A

DETAIL B
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW



SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	3.07	3.32	3.57	
A1	0.40	0.50	0.60	
A2	2.67	2.82	2.97	
b	0.55	0.60	0.65	
b1	0.55	0.60	0.65	
D		15.0		
E		15.0		
e		1.0		
F		13.0		
G		13.0		
H1	0.22	0.32	0.42	
H2	2.45	2.50	2.55	
aaa			0.15	
bbb			0.10	
ccc			0.15	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF BALLS: 196

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

2. ALL DIMENSIONS ARE IN MILLIMETERS

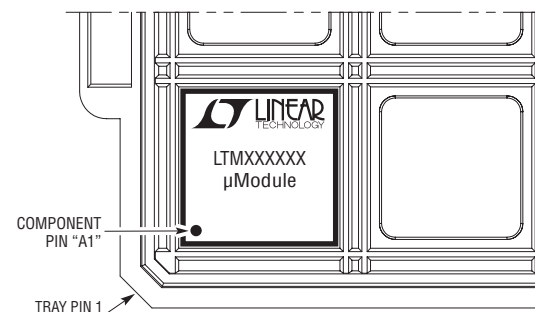
3 BALL DESIGNATION PER JESD MS-028 AND JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu

7  PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION